

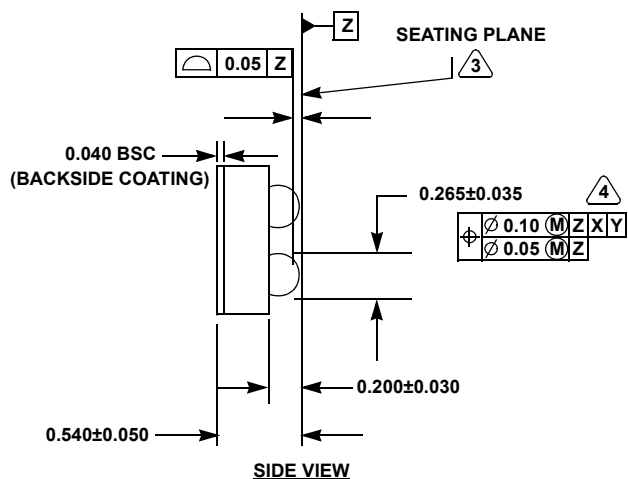
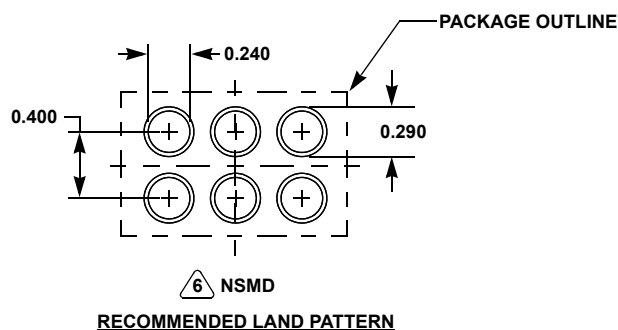
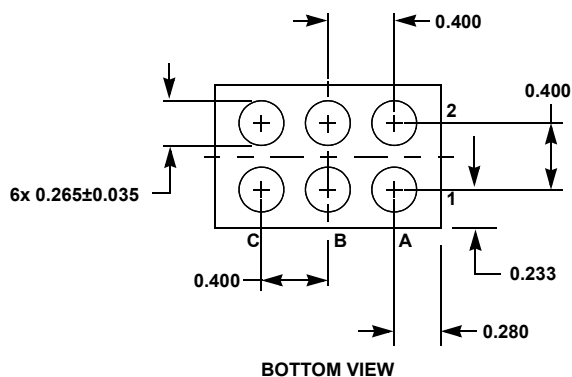
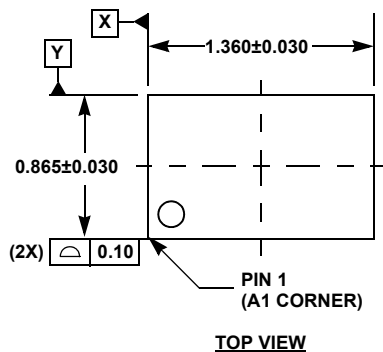
Plastic Packages for Integrated Circuits

Package Outline Drawing

W3x2.6D

6 BALL WAFER LEVEL CHIP SCALE PACKAGE (WLCSP 0.4mm Pitch)

Rev 2, 8/15



NOTES:

1. Dimensions and tolerance per ASME Y 14.5M - 1994.
2. Dimension is measured at the maximum bump diameter parallel to primary datum **Z**.
3. Primary datum **Z** and seating plane are defined by the spherical crowns of the bump.
4. Bump position designation per JESD 95-1, SPP-010.
5. All dimensions are in millimeters.
6. NSMD refers to non-solder mask defined pad design per Intersil Tech Brief TB451 located at:
www.intersil.com/content/dam/Intersil/documents/tb45/tb451.pdf